

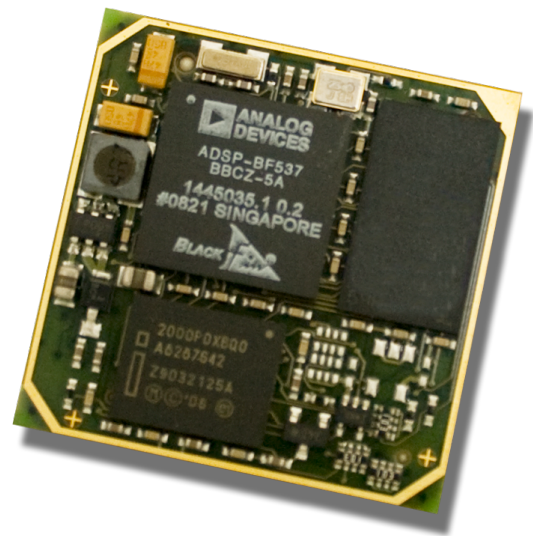
TCM-BF537 Core Module

Blackfin

The TCM-BF537 is an ultra small Core Module designed for industrial temperature range and volume production. It combines Power Supply, RAM and FLASH into a module as small as a chip package. Two 60 pin expansion connectors allow quick prototyping. The module is also available with Border Pads (BP) or a Ball Grid Array (BGA) for low height integrations into the final product.

Features

CPU	Analog Devices BF537 @ 500MHz	
RAM	32MB SDRAM up to 133MHz	
FLASH	8MB	
INTERFACES	CAN	1
	ETHERNET	1x10/100 MBit Ethernet MII/RMII
	PPI	1
	SPI	1
	SPORT	1
	TWI/I²C	1
	UART	2
ADDITIONAL FEATURES	Single 3.3V supply voltage On-board core voltage regulator Low voltage reset circuit	
TEMP. RANGE	-40 to +85 °C	
VERSIONS	Connector, Ball Grid Array, Border Pad	
DIMENSIONS	28x28mm	



Development Support

- EVAL-BF5xx Evaluation Board
- DEV-BF5xx Development Board
- DEV-BF5xxDA-Lite Development Board
- BLACKSheep VDK Framework
- uClinux Port available

Target Applications

- Industrial Automation & Control
- Industrial Handheld Applications
- Medium to High Volume Applications

BLUETECHNIX MECHATRONISCHE SYSTEME GMBH

Lainzerstraße 162/3
1130 Wien, Austria
www.bluetechnix.com

Tel.: +43 (1) 9142091 x 0
Fax.: +43 (1) 9142091 x 99
Email: office@bluetechnix.at

